

FORM PTO-1595 (Modified)
(Rev. 03-01)
OMB No. 0651-0027 ,exp.5/31/2002)
POB/REV03

06-14-2002



U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

102123620

Tab settings

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies): 6-4-02
Yutaka Tsukada
Kimihiro Yamanaka

Additional names(s) of conveying party(ies) Yes No

2. Name and address of receiving party(ies):

Name: International Business Machines Corporation

Internal Address: _____

Street Address: New Orchard Road

City: Armonk State: NY ZIP: 10504

Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance:

Assignment Merger

Security Agreement Change of Name

Other _____

Execution Date: 5/27/02

4. Application number(s) or patent numbers(s): 10162830

If this document is being filed together with a new application, the execution date of the application is: 5/27/02

A. Patent Application No.(s) _____

B. Patent No.(s) _____

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Lawrence R. Fraley

Internal Address: _____

06/14/2002 TDIAZ1 00000038 090457 10162830

01 FC:581 40.00 CH

Street Address: IBM Corporation, IP Law N50/040-4,
1701 North Street

City: Endicott State: NY ZIP: 13760

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41):.....\$ 40.00

Enclosed - Any excess or insufficiency should be credited or debited to deposit account

Authorized to be charged to deposit account

8. Deposit account number: 09-0457

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Lawrence R. Fraley, Reg. No. 26,885

Name of Person Signing _____ Signature Lawrence R. Fraley Date June 4, 2002

Total number of pages including cover sheet, attachments, and document: 3

IBM Docket No.:
JP920010068US1

ASSIGNMENT

Whereas, we

Inventor and City	(1) Yutaka Tsukada County of --	City of Kouga-gun, Shiga-ken and State of Japan
and	(2) Kimihiro Yamanaka County of --	City of Kouga-gun, Shiga-ken Japan and State of Japan
and	(3) County of	City of and State of
and	(4) County of	City of and State of
and	(5) County of	City of and State of
and	(6) County of	City of and State of
and	(7) County of	City of and State of
and	(8) County of	City of and State of

have invented certain improvements in

Title **BALL GRID ARRAY MODULE AND METHOD OF MANUFACTURING SAME**

Dates That Inventors Signed the Declaration **and have executed, respectively, a United States patent application therefor on**

(1)	<u>05/27/102</u>	and,	(2)	<u>05/27/02</u>	and,
(3)	_____	and,	(4)	_____	and,
(5)	_____	and,	(6)	_____	and,
(7)	_____	and,	(8)	_____	

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we the above named hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

(Signatures of Inventors on Page 2)

IBM Docket No.:
JP920010068US1

ASSIGNMENT (Continued)

Title **BALL GRID ARRAY MODULE AND METHOD OF MANUFACTURING SAME**

City Date (1) Signed at Yasu, Japan
on 05/27/02

Yutaka Tsukada
(Signature of Inventor)

Yutaka Tsukada
(Typed Name of Inventor)

City Date (2) Signed at Yasu, Japan
on 05/27/02

Kimihiko Yamanaka
(Signature of Inventor)

Kimihiko Yamanaka
(Typed Name of Inventor)

City Date (3) Signed at
on _____

(Signature of Inventor)

(Typed Name of Inventor)

City Date (4) Signed at
on _____

(Signature of Inventor)

(Typed Name of Inventor)

City Date (5) Signed at
on _____

(Signature of Inventor)

(Typed Name of Inventor)

City Date (6) Signed at
on _____

(Signature of Inventor)

(Typed Name of Inventor)

City Date (7) Signed at
on _____

(Signature of Inventor)

(Typed Name of Inventor)

City Date (8) Signed at
on _____

(Signature of Inventor)

(Typed Name of Inventor)